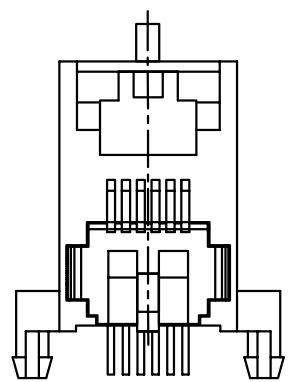
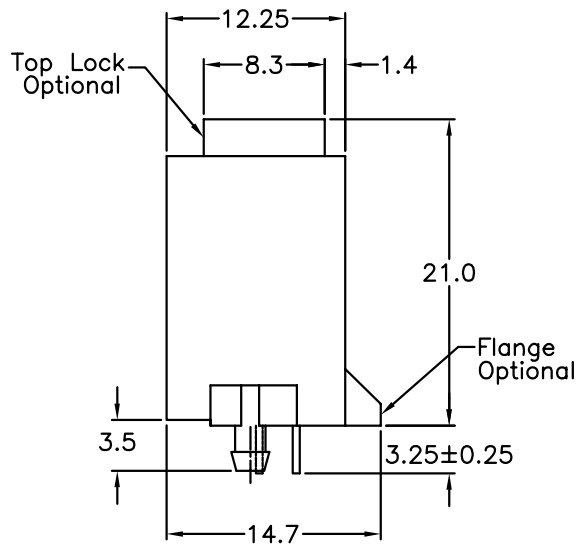
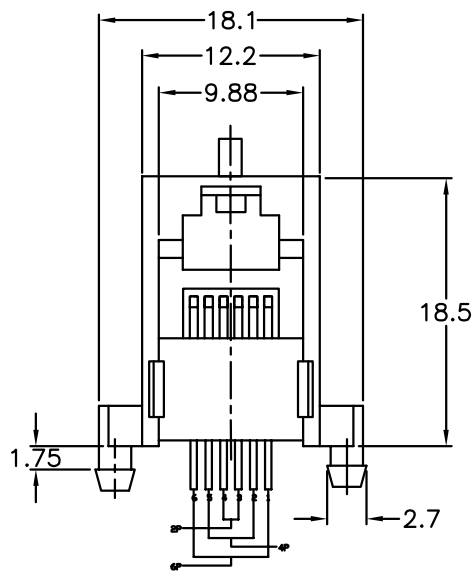


REV.	SPECIFICATION	ECN NO.	APPD.



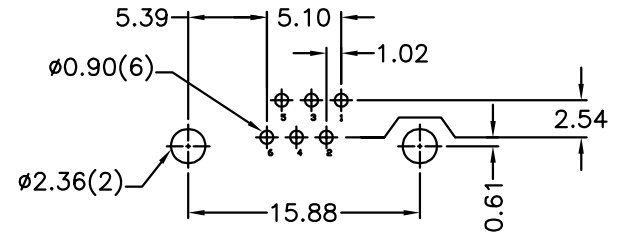
**Material:**

Housing: 30% Glass Filled PBT UL94V-0.  
 Contacts: Phosphor Bronze.  
 Plating: Gold plated on contact area over Nickel.

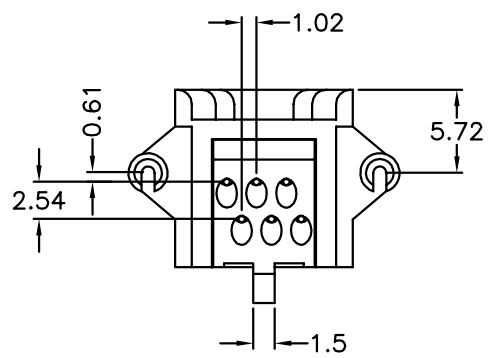
**Electrical Characteristics:**

Current Rating: 1 AMP.  
 Insulator Resistance: 500MΩ min. at DC100V.  
 Contact Resistance: 30mΩ max. at DC 100mA.  
 Operating Temperature: -40°C ~ +85°C.

**\*RoHS Compliant**



P.C. Board Layout



<u>8949-G</u>	<u>6</u>	<u>6</u>	<u>/06</u>	<u>B</u>	<u>A</u>
Series	Position	6: 6 Contacts	06: 06 μ" Gold Plated 15: 15 μ" Gold Plated 30: 30 μ" Gold Plated 50: 50 μ" Gold Plated	B: Black Y: Grey	A: Tray Package

<b>Tolerances</b> x = ±0.5 .x = ±0.25 .xx = ±0.15	<b>Drawn No.</b>	8949D02122		<b>Title:</b> 8949 Series Modular Jack	 <b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N: 8949-G66/06BA	
	<b>Projection</b>					
	<b>Unit</b>	mm	<b>Scale</b>			1:1
	<b>Drawn By</b>	Liling	<b>Date</b>			04/17'08
					<b>SHEET</b> 1/1 <b>Ver.No.</b> A2	